

PERFORMANCE SPECIFICATION

SWITCHES AND SWITCH ASSEMBLIES, SENSITIVE, SNAP ACTION
(BASIC, LIMIT, PUSH BUTTON AND TOGGLE SWITCHES),
GENERAL SPECIFICATION FOR

This amendment forms a part of MIL-PRF-8805E, dated 23 January 1998, and is approved for use by all Departments and Agencies of the Department of Defense.

PAGE 6

3.5.2.2, delete and substitute:

" 3.5.2.2 Printed circuit board terminals. Terminals intended for direct soldering into printed circuit boards shall be metal alloy plated or solder dip. Tin-lead composition may be used. Plating shall be 100 microinches minimum. For additional information and guidance on tin-lead plating and hot solder dip see 6.12."

3.5.2.4, delete and substitute:

" 3.5.2.4 Plug-in terminations (not applicable to printed circuit boards). Terminals shall be double plated with an underplate of .000030 inches minimum (0.000076 mm minimum) thick. Gold plated with nickel underplate is one double plated combination. For additional information and guidance on gold and nickel plating see 6.12."

PAGE 19

* 4.7.2, delete and substitute:

"4.7.2 Solderability (see 3.6) Solder type terminations shall be tested in accordance with method 208 of MIL-STD-202. A minimum of two terminals per switch shall be tested."

PAGE 20

- * 4.7.3.3b, delete and substitute:

“b. Leakage-rate sensitivity shall be 1×10^{-6} atm cm³/s under standard conditions.”

- * 4.7.3.4b, delete and substitute:

“b. Leakage-rate sensitivity shall be 1×10^{-8} atm cm³/s under standard conditions.”

PAGE 37

- * 4.7.34, first sentence, delete and substitute:

“4.7.34 Logic level circuit (when specified, see 3.1) (see 3.38). Switches shall be tested in accordance with EIA RS 448-4, method 17 as follows:”

Custodians:

Army - CR
Navy - EC
Air Force - 11
NASA - NA

Preparing activity:
DLA - CC

(Project 5930-1761)

Review activities:

Army - AR, AV, MI
Navy - AS, MC, OS, SH
Air Force - 19